

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Title: COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC COOLING

Docket No.: 303.533US2

Filed: June 26, 2003

Examiner: James M. Mitchell

Customer No.: 21186

Serial No.: 10/606,539

Due Date: January 6, 2005

Group Art Unit: 2813

Confirmation No.: 5770

Commissioner for Patents

Attn: MAIL STOP ISSUE FEE

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